Since Apple unveiled iPhone, the smartphone industry has been on a phenomenal growth vector. With more than 10% growth in mobile device shipments, smartphone sales in the Asia-Pacific region have overtaken the US and Europe regions. Some common trends in Asia-Pacific Region are multi-core CPU chipsets, thin smartphones, smaller battery-size and low-cost smartphones. Immense challenges are encountered in enabling the smartphones for an inclusive world. This talk will cover the techniques in meeting the smart goals on Power, Performance, Area, Thermal and Schedule. The talk will also cover how leadership in Smartphone chipset design is very key in enabling the newer markets of IoT.

**Biography:** Venugopal Puvvada has been Vice-President, Engineering at Qualcomm Bangalore Design Center, for the past nine years. Currently he is responsible for Central Engineering and Technology Team. At Qualcomm Venu was responsible for more than 50 tapeouts and has driven Chip cost reduction, Combined Verification Strategies, Power Optimization and High Performance cores. Venu has more than 22 years of experience and worked in the areas of ASIC CAD/Methodology, Chip Design, Physical implementation, Power optimization, Digital IP development, Chip Cost Optimization and Library Development. Before joining Qualcomm, Venu worked at TI India for 13 years and was a Senior Member Technical Staff. He has 3 patents accepted, 2 more filed and several technical publications to his credit. Venu has been on Low Power Panels at DAC and VLSI Design Conferences. Venu has done M.S (Micro-electronics) in 1993 and B.Tech in 1991 from I.I.T. Madras.